## F/HCWo6 LF

#### **Electrical and Acoustical Parameter**

Rated voltage (VDC) 6.0

Operating voltage (VDC) 4.0 – 8.0

Rated current (mA/max.) \*

Sound pressure level (dBA/10cm/min.) \* 90

Resonant Frequency (Hz/±300) 2200

Remark: \*Applying rated voltage

### Mechanical, Environmental Parameter

Contact / Wire Pin

Operating temperature (°C) -20 to +70

Storage temperature (°C) -30 to +80

Material housing PPO

Color housing Black

Component weight (g) 3.0

Remark:

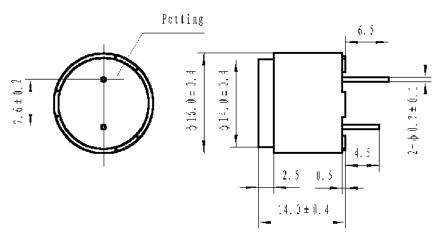
### <u>Approval</u>

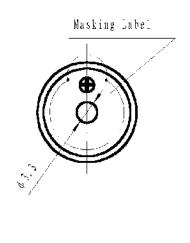
RoHs ✓

UL  $\square$ 

#### **Drawing of Component**

Unit:mm

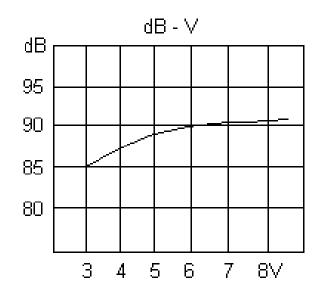


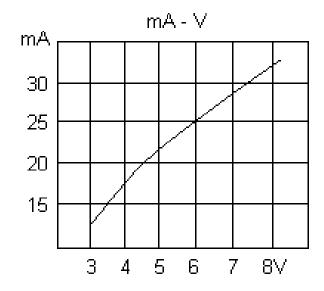


Designed by	KH	05.01.2012	Dimensions without tolerance ±0.5mm Index: 00		Current date
Released by	BB	05.01.2012	Drawing number	DDB	05.01.2012
Changed by			120105.1PDB		Page 1 of 5

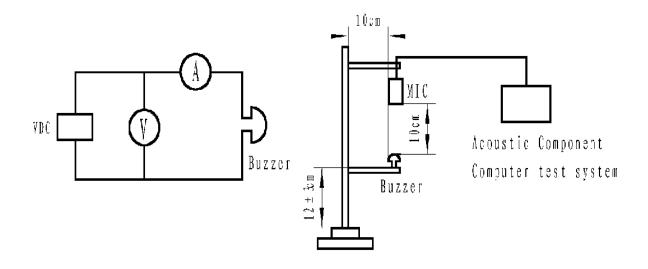
## F/HCWo6 LF

### Input Voltage VS. Sound Pressure Level & Current Consumption





### Test method



ı	Designed by	KH	05.01.2012	Dimensions without tolerance ±0.5mm	Index: oo	Current date
I	Released by	BB	05.01.2012	120105.1PDB		05.01.2012
I	Changed by					Page 2 of 5

## F/HCWo6 LF

### **Reliability test**

NO.	ITEM	TESTING CONDITION	VARIANCE AFTER TEST
1	Humidity	40±5°C, 93(+2/-3)%RH, 96HRS	
2	High temp.	+75±2°C, 96HRS	
3	Low temp.	-30±2°C, 96HRS	Sound pressure level
4	Temperature Cycling	-30±2°C, 30minutes room temp. 15 minutes +75±2°C, 30 minutes room temp. 15 minutes 5 cycles	initial value±10dB  Max. current value±10%mA
5	Drop test	3 times from height of 70cm onto the surface of 10mm thick wooden board.	Oscillating frequency
6	Vibration test	Make the test for the directions of X Y and Z (total 0.5 hours).  To-and-fro. sweep time (from 10 to 55 Hz and then from 55 to 10Hz) under single amplitude of 1.0mm is 1 minute.	value±300Hz.
7	Solder heat resistance	The part leads (pins) shall be immersed in molten solder maintained at 250±10°C for a period of 30 seconds.	After the test part shall meet specifications without any degradation in appearance and performance.

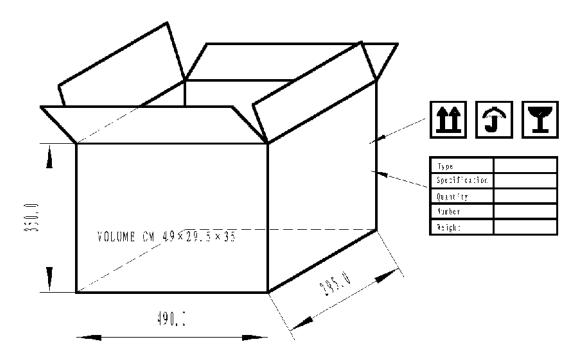
### Recommended Temp. Profile for Reflow Oven (Fig.1)

n.a.

Designed by	KH	05.01.2012	Dimensions without tolerance ±0.5mm	Index: oo	Current date
Released by	BB	05.01.2012	<b>120105.1PDB</b>		05.01.2012
Changed by					Page 3 of 5

## F/HCWo6 LF

### **Packaging Information**



#### **NOTES:**

- 1. 50 PCS per box
- 2. Total 40 boxes per carton
- 3. Total 2000 PCS carton
- 4. Volume:  $49 \times 29.5 \times 35$ cm

Designed by	KH	05.01.2012	Dimensions without tolerance ±0.5mm Index: 00		Current date
Released by	BB	05.01.2012	120105.1PDB		05.01.2012
Changed by					Page 4 of 5



## F/HCWo6 LF

### **Revision Table**

Index Nr.	Date Reason - Procedure Change description	Drawing Date	implementation LS-Nr.: Date	Comments

Designed by	KH	05.01.2012	Dimensions without tolerance ±0.5mm	Index: oo	Current date
Released by	BB	05.01.2012	Drawing number	DDD	05.01.2012
Changed by			120105.1PDB		Page 5 of 5